

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB200N25N3 G	**Issued**	08. April 2022
MA#	MA005711177		
Package	PG-TO263-3-2	**Weight***	1570.52 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.562	1.12	1.12	11183	11183
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		194	
	non noble metal	copper	7440-50-8	304.026	19.36	19.39	193583	193835
wire	non noble metal	aluminium	7429-90-5	13.738	0.87	0.87	8747	8747
encapsulation	inorganic material	zincoxide	1314-13-2	6.662	0.42		4242	
	miscellaneous	miscellaneous	-	26.649	1.70		16968	
	plastics	epoxy resin	-	99.935	6.36		63632	
	inorganic material	silicondioxide	60676-86-0	532.987	33.94	42.42	339369	424211
leadfinish	non noble metal	tin	7440-31-5	9.657	0.61	0.61	6149	6149
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.206	0.01		131	
	noble metal	silver	7440-22-4	0.258	0.02		164	
	non noble metal	lead	7439-92-1	9.839	0.63	0.66	6265	6560
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.03		349	
	non noble metal	copper	7440-50-8	547.666	34.88	34.92	348715	349169
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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